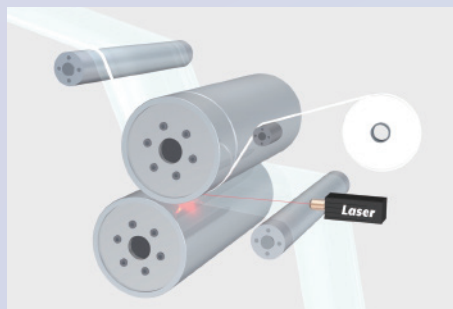


Zipper for Laser Diode Sealing

Zipper for Laser Diode Sealing

Features



Concept image

- Laser energy selectively melts only the sealant layer
- Zipper width reduced from 12 mm to just 3 mm
- No heat-sealing unit is required on the pouch-making machine
- Jointly developed with Totani Corporation

Benefits

● Improved Pouch Appearance

Localized heating reduces zipper deformation and heat damage to the film. It also provides an attractive finish for mono-material packaging

● Less Plastic, Fewer Resources

The narrower zipper reduces resin use and environmental impact

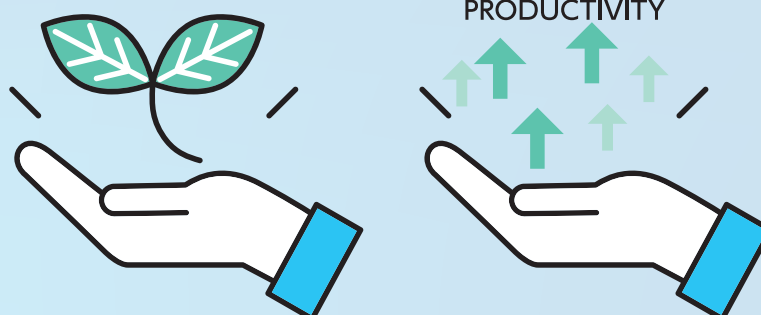
● Energy and Space Savings

No heat-sealing unit is required, reducing power consumption and equipment footprint. *Compared with conventional systems

● Increased Productivity

High-speed sealing offers the potential for even faster pouch production

Sustainability Meets Productivity



※Data in this catalogue shows sample figures measured under certain specific conditions.
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